



1 meq

AF/2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Salman Akram	§	Group Art Unit:	2827
		§		
Serial No.:	09/853,111	§		
		§	Examiner:	A. Chambliss
Filed:	May 10, 2001	§		
		§		
For:	Method of Fabricating Mounted Multiple Semiconductor Dies In A Package (As Amended)	§	Atty. Dkt. No.:	MCT.0012D1US (97-0141)
		§		
		§		

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the Final Rejection, please amend the above-referenced patent application as follows:

Date of Deposit: August 7, 2003

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

Cynthia L. Hayden
Cynthia L. Hayden